

Electronic Acknowledgement Receipt

EFS ID:	1353533
Application Number:	10750059
International Application Number:	
Confirmation Number:	9129
Title of Invention:	Solder ball pad structure
First Named Inventor/Applicant Name:	Hiroshi Miyazaki
Customer Number:	23494
Filer:	Yingsheng Tung/Jackie McBride
Filer Authorized By:	Yingsheng Tung
Attorney Docket Number:	TI-36833
Receipt Date:	05-DEC-2006
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Application Type:	Utility

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File Listing:

Document Number	Document Description	File Name	File Size(Bytes)	Multi Part /.zip	Pages (if appl.)
1		TI-36833_1_111.pdf	68034	yes	5

Multipart Description/PDF files in .zip description		
Document Description	Start	End
Amendment - After Non-Final Rejection	1	1
Claims	2	4
Applicant Arguments/Remarks Made in an Amendment	5	5

Warnings:	
Information:	
Total Files Size (in bytes):	68034

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New Applications Under 35 U.S.C. 111
If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.

National Stage of an International Application under 35 U.S.C. 371
If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.